HI-P INTERNATIONAL LIMITED

(Company Registration No.: 198004817H) (Incorporated in the Republic of Singapore)

PAID-UP CAPITAL OF HI-P (SUZHOU) ELECTRONICS TECHNOLOGY CO., LTD.

The Board of Directors of Hi-P International Limited (the "Company", and together with its subsidiaries, the "Group") refer to its announcement dated 14 January 2019 ("Announcement") in relation to the increase in registered capital of its indirect wholly-owned subsidiary, Hi-P (Suzhou) Electronics Technology Co., Ltd. ("Subsidiary").

Further to the Announcement, the Board wishes to announce that Hi-P Flex Pte. Ltd. (a wholly-owned subsidiary of the Company) has paid up USD10 million of the registered capital of the Subsidiary. Accordingly, the registered capital of the Subsidiary has been paid up in full.

The Company, through its wholly-owned subsidiary, Hi-P Flex Pte. Ltd., continues to own 100% of the Subsidiary after such pay up of the Subsidiary's registered capital.

The sum of USD10 million was funded through the Group's internal resources and is not expected to have any material impact on the Group's earnings per share and net tangible assets per share for the financial year ending 31 December 2019.

None of the directors or substantial shareholders of the Company have any interest, direct or indirect (other than through their shareholdings in the Company), in the above transaction.

By Order of the Board

Yao Hsiao Tung
Executive Chairman and Chief Executive Officer

26 February 2019